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Standardizacija toplotnih lastnosti pri polprevodniških ohišjih - 6. del: Model toplotne upornosti in kapacitivnosti za napoved prehodne temperature na spojih in merilnih točkah (IEC 63378-6:2026)

Thermal standardization on semiconductor packages - Part 6: Thermal resistance and capacitance model for transient temperature prediction at junction and measurement points (IEC 63378-6:2026)

Thermische Normung an Halbleitergehäusen - Teil 6: Wärmewiderstandsmodell für die Vorhersage der vorübergehenden Temperatur an Sperrschicht- und Messpunkten (IEC 63378-6:2026)

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NORME EUROPÉENNE

EUROPÄISCHE NORM

EN IEC 63378-6

March 2026

ICS 31.080.01

English Version

Thermal standardization on semiconductor packages - Part 6: Thermal resistance and capacitance model for transient temperature prediction at junction and measurement points (IEC 63378-6:2026)

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(IEC 63378-6:2026)

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European foreword

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CONTENTS

FOREWORD ... 3
INTRODUCTION ... 5
1 Scope ... 6
2 Normative references ... 6
3 Terms and definitions ... 6
4 Definition of DXRC ... 6
4.1 General ... 6
4.2 Thermal resistance and capacitance (RC) topology of DXRC ... 7
4.2.1 Thermal RC topology of DXRC ... 7
4.2.2 Outline of DXRC ... 8
4.2.3 RC values on NJA-RC ... 8
4.2.4 RC values on MPA-RC ... 8
Annex A (informative) Accuracy verification of DXRC model for TO-252 ... 10
A.1 General ... 10
A.2 CFD model ... 10
A.3 Calculation of thermal RC values ... 12
A.4 MPA-RC and DXRC model outline ... 13
A.5 Optimization of RC values in MPA-RC ... 13
A.6 Result ... 15
Annex B (informative) Accuracy verification of DXRC model for TO-263 ... 16
B.1 General ... 16
B.2 CFD model ... 16
B.3 Calculation of thermal RC values ... 18
B.4 MPA-RC and DXRC model outline ... 19
B.5 Optimization of RC values in MPA-RC ... 19
B.6 Result ... 20
Annex C (informative) Accuracy verification of DXRC model for HSOP ... 21
C.1 General ... 21
C.2 CFD model ... 21
C.3 Calculation of thermal RC values ... 23
C.4 MPA-RC and DXRC model outline ... 24
C.5 Optimization of RC values in MPA-RC ... 24
C.6 Result ... 25
Annex D (informative) The effect of PCB layers ... 26
D.1 General ... 26
D.2 Verification method ... 26
D.3 Result ... 26
Bibliography ... 28

Figure 1 – Thermal RC topology of DXRC ... 7
Figure 2 – Outline of DXRC ... 8
Figure A.1 – CFD model for TO-252 ... 10
Figure A.2 – Size of TO-252 package ... 11
Figure A.3 – Structure function ... 12

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Figure A.4 – Result of verification ... 15
Figure B.1 – CFD model for TO-263 ... 16
Figure B.2 – Size of TO-263 package ... 17
Figure B.3 – Structure function ... 18
Figure B.4 – Result of verification ... 20
Figure C.1 – CFD model for HSOP ... 21
Figure C.2 – Size of HSOP package ... 22
Figure C.3 – Structure function ... 23
Figure C.4 – Result of verification ... 25
Figure D.1 – Comparisons of temperature rise between the detailed model and the DXRC model ... 27

Table A.1 – Material attributes ... 11
Table A.2 – Thermal resistances in NJA-RC ... 12
Table A.3 – Thermal capacitances in NJA-RC ... 13
Table A.4 – Input variables ... 14
Table A.5 – Optimized RC values ... 14
Table B.1 – Material attributes ... 17
Table B.2 – Thermal resistances in NJA-RC ... 18
Table B.3 – Thermal capacitances in NJA-RC ... 19
Table B.4 – Optimized RC values ... 20
Table C.1 – Material Attributes ... 22
Table C.2 – Thermal resistances in NJA-RC ... 23
Table C.3 – Thermal capacitances in NJA-RC ... 24
Table C.4 – Optimized RC values ... 25
Table D.1 – Combination of the coverages of copper layers ... 26

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The language used for the development of this International Standard is English.

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